Welcome to O-leading

O-Leading strives to be your one stop solution partner in EMS supply chain, including PCB design , PCB fabrication and PCB assembly ,We provide some of the most advanced PCB technology, including HDI PCBs,multilayer PCBs, Rigid-Flexible PCBs.We can support from quick turn prototype to medium & mass Production.

In general, our global customers are very impressed with our services:Rapid response, competitive price and quality commitment.Providing more valuable technical service and overall solution is the way Oleading forward.

Looking to the future, O-leading will concentrate on the innovation and development of electronics manufacturing technology as always, and make persistent efforts on PCB & PCBA one-stop service to provide first-class services and create more value for our customers.

PLEASE CLICK THESE FOR MORE INFORMATION Low Cost PCB Fabrication POE Oem Manufacturing



Product Description

Raspberry Pi PoE Feature Compute Module IO Board (**China Half Hole Module Circuit Board Manufacturer**)

Overview

The Compute Module PoE Board is a development board which you can plug a Raspberry Pi Compute Module into, and make use of the resources of Pi more flexibly. With the PoE (Power over Ethernet) feature, and versatile onboard peripheral interfaces, it is suitable for evaluating the Raspberry Pi compute module, also is an ideal choice for end products.

Features

- * Raspberry Pi GPIO header, for connecting sorts of Raspberry Pi HATs
- * 10/100M auto-negotiation Ethernet port, with PoE enabled
- * 4x USB ports, allows connecting more USB devices
- * 2x CSI camera interfaces
- * Onboard HDMI / DSI interfaces for connecting displays
- * Onboard USB TO UART, for serial debugging
- * Cooling fan interface, auto run on power up OR controlled by IO pins
- * Adopts isolated SMPS (Switching Mode Power Supply)

Specifications

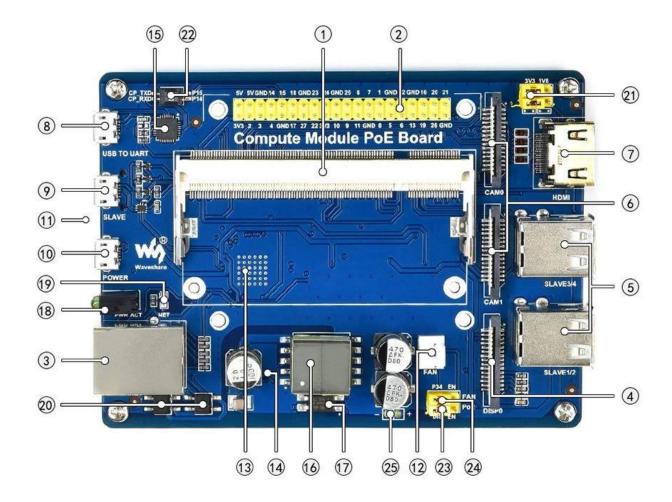
* Power supply: micro USB port / PoE Ethernet port

* PoE power input: 37V ~ 57V DC in * PoE power output: 5V 2.5A DC out

* Network standard: 802.3af PoE standard

* Dimensions: 114mm × 84.4mm * Mounting hole size: 3.2mm

What's on Board



- 1. Compute Module interface: for connecting Compute Module (CM3 / CM3L / CM3+ / CM3+L)
- 2. Raspberry Pi GPIO header: for connecting Raspberry Pi HATs
- 3. PoE enabled Ethernet port: 10/100M auto-negotiation, for connecting router or switch with PoE function
- 4. DSI interface: display ports, for connecting Raspberry Pi LCD
- 5. USB ports: 4x USB ports, for connecting USB devices
- 6. CSI interface: 2x CSI camera ports, for connecting Raspberry Pi Camera
- 7. HDMI port
- 8. USB TO UART interface: for serial debugging
- 9. USB SLAVE interface: allows you to burn system image into Compute Module 3/3+
- 10. Power port: 5V 2.5A
- 11. TF card slot (bottom side): insert a Micro SD card with pre-burnt system, to start up Compute Module 3/3+ Lite variant
- 12. Cooling fan interface
- 13. LAN9514 (bottom side): fully-integrated USB hub and 10/100M Ethernet controller
- 14. Si3404 PoE power management chip (bottom side)
- 15. CP2102 USB TO UART converter
- 16. EP13 PoE power transformer
- 17. Optical isolator
- 18. Two LED indicators:

Red: Raspberry Pi power indicator

Green: Raspberry Pi operating status indicator

- 19. NET network indicator
- 20. Bridge rectifier
- 21. VGx power config jumper: config the I/O level
- 22. UART output config:

Left: connect the CP2102 serial port and Raspberry Pi serial port Right: disconnect the CP2102 serial port and Raspberry Pi serial port

23. Cooling fan config:

P34: the fan is program controlled via P34 pin

EN: the fan is directly powered from 5V power supply

24. PoE config:

DIS: disable PoE EN: enable PoE

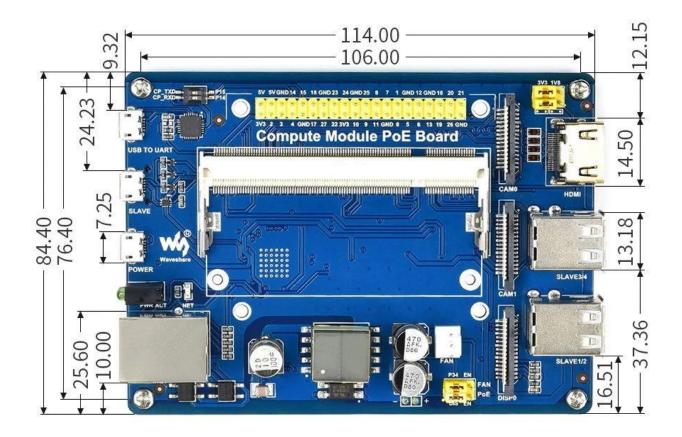
25. PoE power voltage measuring pads

Example



Note: compute module in the photo is NOT included.

Dimensions



Our Team

To be #ELIABLE

Quality first ,

Customer supreme,

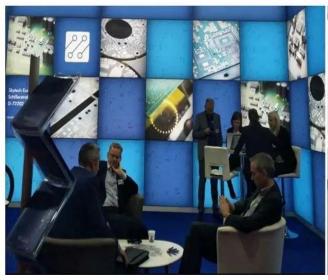
Scientifically management,

Striving for famous brand





THE CUSTOMER IS KING





To be VALUABLE

Science and technology keeps head ,

Put people first,

Be precise and practical,

contribute sincerely

Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT





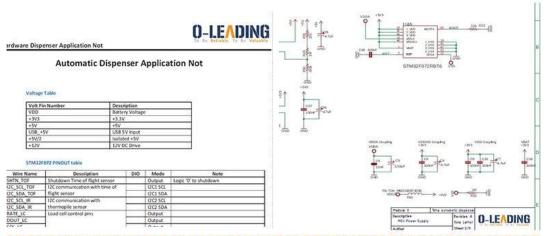








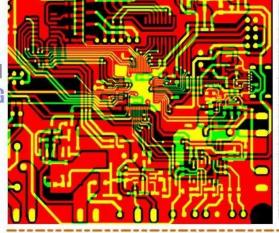
HOW O-LEADING MAKE A PROJECT FOR YOU



HARDWARE schematics

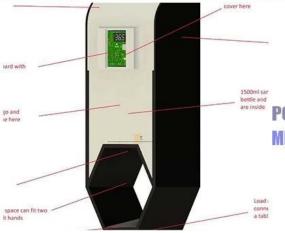
PCB PRODUCTION COMPONNETS SOURCING





Qty	Value	Device	Parts	Description
4	AK500/2	AK500/2	X1, X2,	CONNECTOR
1	AK500/3	AK500/3	X7	CONNECTOR
1	1241148	MA04-2	SV2	8,000 F. 100,11 S. 10 (10,000
1	PPPC04	MA04-2	SV1	8 POS , 4*2 FEMALE PIN HEADE
1	ML10	ML10	SV4	HARTING
1	8MHZ	XTALL_CSTCE8M	X5	STCE8M00G52-R0 RESONATOR
1	OR	R-0603	R53	Thick Film Resistors - SMD 0603
2	10R	R-0603	R12, R5	Thick Film Resistors - SMD 0603
8	100R	R-0603	R1, R2,	Thick Film Resistors - SMD 0603
1	270R	R-0805	R15	Thick Film Resistors - SMD 0605
1	330R	R-0603	R11	Thick Film Resistors - SMD 0603
9	680R	R-0603	R20, R3	Thick Film Resistors - SMD 0603
17	1k	R-0603	R9, R10	Thick Film Resistors - SMD 0603
2	4.7k	R-0603	R17, R6	Thick Film Resistors - SMD 0603
2	5.1k	R-0603	R18, R1	Thick Film Resistors - SMD 0603
9	10k	R-0603	R16, R3	Thick Film Resistors - SMD 0603
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PCB Assembly **MECHANICAL DESIGN**





































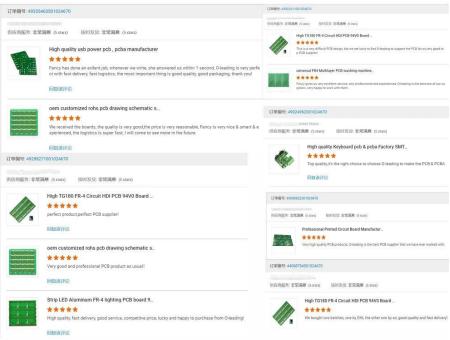


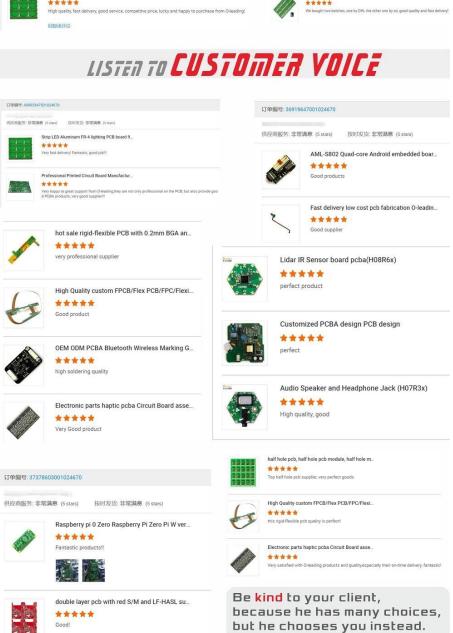




D-LEADING CUSTOMER REVIEW

customaa voica is **extraemely important** to us







Certifications

O-LEADING *TRANING*



Кеер *L Е Д Я Л Л Б*

There's a phrase in Buddhism, 'Beginner's mind.'

lt's wonderful to have a beginner's mind

WE HAVE A DREAM

Кеер *аппппБ*

I would like to live to study and not study to live.

----Bacon









Test Report

No. SZXEC1900530401

Date: 30 Mar 2019

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313.FLOOR 13. FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG,

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : Date of Sample Received: 22 Mar 2019

RP19-005089 - SZ

22 Mar 2019 - 30 Mar 2019

Testing Period : Test Requested :

Selected test(s) as requested by client.

Test Method :

Please refer to next page(s).

Test Results :

Please refer to next page(s).

Conclusion:

Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyl sign (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phihalates such as Bis(2-ethylnexyl) phihalate (DEHP), Butyl benzyl phihalate (BBP), Dibutyl phihalate (DBP), and Disobutyl phihalate (DBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

lina

Tina Fan Approved Signatory



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SGS

No. SZXEC1900530401

Date: 30 Mar 2019

Page 2 of 6

Test Report Test Results :

Test Part Description:

SN1

SGS Sample ID SGS Sample ID Description SZX19-005304.001 Green"PCB"

(1) 1 mg/kg = 1 ppm = 0.0001% (2) MDL = Method Detection Limit

(3) ND = Not Detected (< MDL)

(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC62321-5:2013, IEC62321-7-2:2017, IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s) Limit Unit Cadmium (Cd) 100 ND mg/kg Lead (Pb) 1,000 Mercury (Hg) Hexavalent Chromium (Cr(VI)) 1.000 Sum of PBBs ND 1.000 mg/kg Monobromobiphenyl ND ND ND Dibromobiphenyl Tribromobiphenyl mg/kg mg/kg mg/kg mg/kg ND ND ND Tetrabromobiphenyl Pentabromobiphenyl Hexabromobiphenyl mg/kg mg/kg mg/kg Heptabromobiphenyl ND ND ND ND Octabromobiphenyl Nonabromobiphenyl Decabromobiphenyl mg/kg mg/kg mg/kg ND ND ND Sum of PBDEs 1,000 Monobromodiphenyl ethe Dibromodiphen yl ether mg/kg Tribromodiphenyl ether mg/kg ND Tetrabromodiphenyl ether Pentabromodiphenyl ether



Max

Max

UL Product iQ™



ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

Cond Width

O-LEADING SUPPLY CHAIN (HK) CO LTD

E490354

ROOM 1205, 12/F TAI SANG BANK BLDG 130-132 DES VOEUS ROAD CENTRAL, HONG KONG

		Min	Cond	SS/	Area	Solo	der	Oper		Meets	c
	Min	Edge	Thk	DS/	Diam	Lim	its	Temp	Flame	UL796	T
Type	mm(in)	mm(in)	mic(mil)	DSO	mm(in)	c	sec	c	Class	DSR	1
Multilayer (m	Multilayer (mass laminate) printed wiring boards.										
O-LEADING- 401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	100	:70
O-LEADING- 407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer pri	Multilayer printed wiring boards.										\neg
O-LEADING- 408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer p	Single layer printed wiring boards.										
O-LEADING- 002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING- 003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	A	200
O-LEADING- 033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING- 205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	120
O-LEADING- 206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	==
O-LEADING- D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING- S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING- S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	НВ	A	*
O-LEADING- S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

 $[\]mbox{\ensuremath{\star}}$ - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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Process Capability							
PCB Production Capabilities							
Layer Count	1Layer-32Layer						
Finished copper thickness	1/3oz-12oz						
Min Line width/spacing internal	3.0mil/3.0mil						
Min Line width/spacing external	4.0mil/4.0mil						
Max Aspect Ratio	10:1						
Board thickness	0.2mm-5.0mm						
Max Panel size(inches)	635*1500mm						
Minimum Drilled Hole Size	4mil						
Plated Hole Tolerance	+/-3mil						
Blind/Buried Vias (All Types)	YES						
Via Fill(Conductive, Non-Conductive)	YES						
Base Material	FR-4,FR-4high Tg.Halogen fi	ree material,Rogers,Aluminium base,Polyimide,Heavy Copper					
Surface finishes	HASL,OSP,ENIG,HAL-LF,lm	mersion silver,lmmersion Tin,Gold fingers,Carbon ink					
SMT Production Cap	pabilities 						
PCB Material		FR-4,CEM-1,CEM-3,Aluminum-based board,FPC					
Max PCB size		510x1500mm					
Min PCB size		50x50mm					
PCB Thickness		0.5mm-4.5mm					
Board thickness		0.5-4mm					
Min Components size		0201					
Standard chip size comp	onent	0603 and larger					
Component max height		15mm					
Min lead pitch		0.3mm					
Min BGA ball pitch		0.4mm					
Placement precision		+/-0.03mm					

Packaging & Delivery

Shipping service











Quick Turn Lead Time						
Layer Count:	Lead Tim	Special Requirement				
1L/2L	2-3days	24 Hours,48 Hours				
4L	3-4days	48 Hours				
6L	4-5days	72 Hours				
8L	5-6days	NA				
10L	6-7days	NA				
12L	7-8days	NA				
14L	8-9days	NA				

Standard Lead Time						
Layer Count:	Sample Lead Time	Volume order lead time				
2L	4 days	10 days				
4L	5 days	11 days				
6L	6 days	12 days				
8L	8 days	14 days				
10L	10 days	16 days				
12L	12 days	18 days				
14L	14 days	20 days				
16-32L	18 days	24 days				

FAQ

1. How do O-Leading ensure quality? Our high quality standard is achieved with the following.

- 1.1 The process is strictly controlled under ISO 9001:2008 standards.
- 1.2 Extensive use of software in managing the production process
- 1.3 State-of-art testing equipments and tools. E.g. Flying Probe, X-ray Inspection, AOI (Automated Optical Inspector) and ICT (in-circuit testing).
- 1.4.Dedicated quality assurance team with failure case analysis process
- 1.5. Continuous staff training and education

2. How do O-Leading keep your price competitive?

Over the last decade, prices of many raw materials (e.g. copper, chemicals) had doubled, tripled or quadrupled; Chinese currency RMB had appreciated 31% over US dollar; And our labor cost also increased significantly.

However, O-Leading have kept our pricing steady. This owns entirely to our innovations in reducing cost, avoiding wastes and improving efficiency. Our prices are very competitive in the industry at the same quality level.

We believe in a win-win partnership with our customers. Our partnership will be mutually beneficial if we can provide you an edgeon cost and quality.

3. What kinds of boards can O-Leading process?

Common FR4, high-TG and halogen-free boards, Rogers, Arlon, Telfon, aluminum/copper-based boards, PI, etc.

4. What data are needed for PCB & PCBA production?

- 4.1 BOM (Bill of Materials) with reference designators: component description, manufacturer's name and part number.
- 4.2 PCB Gerber files.
- 4.3 PCB fabrication drawing and PCBA assembly drawing.
- 4.4 Test procedures.
- 4.5 Any mechanical restrictions such as assembly height requirements.

5. What's the typical process flow for multi-layer PCB?

Material cutting \rightarrow Inner dry film \rightarrow inner etching \rightarrow Inner AOI \rightarrow Multi-bond \rightarrow Layer stack up Pressing \rightarrow Drilling \rightarrow PTH \rightarrow Panel Plating \rightarrow Outer Dry Film \rightarrow Pattern Plating \rightarrow Outer etching \rightarrow Outer AOI \rightarrow Solder Mask \rightarrow Component Mark \rightarrow Surface finish \rightarrow Routing \rightarrow E/T \rightarrow Visual Inspection.

6. What's the key equipments for HDI manufacturing?

Key equipment list is as following: Laser drilling machine, Pressing machine, VCP line, Automatic Exposing machine, LDI and etc.

The equipments we have are the best in the industry, laser drilling machines are from Mitsubishi and Hitachi, LDI machines are from Screen(Japan), Automatic Exposing machines are also from Hitachi, all of them make we can meet customer's technical requirements.

7. How many types of surface finish O-lead can do?

O-the leader has the full series of surface finish, such as: ENIG, OSP, LF-HASL, gold plating (soft/hard), immersion silver, Tin, silver plating, immersion tin plating, carbon ink and etc. .. OSP, ENIG, OSP + ENIG commonly used on the HDI, we usually recommend that you use a client or OSP OSP + ENIG if BGA PAD size less than 0.3 mm.

8. What's your capability for FPC? Can O-Leading provide SMT service also?

O-Leading can fabricate FPC from single layer to 8layer, the working panel size can be as large as 2000mm*240mm, please find the details in the page "Flex Capability" We also provide SMT one stop service to customer.

9. What are the main factors which will affect the price of PCB?

Material;

Surface finish;

Technology difficulty;

Different quality criteria;

PCB characteristics;

Payment terms;

Different manufacturing countries.

10. What's the definition of PCB, PWB and FPC and what's the difference?

PCB is short for Printed Circuit Board;

PWB is short for Printed Wire Board, same meaning as Printed Circuit Board;

FPC is short for Flexible Printed Board.

11. What factors should be considered when choosing the material for a PCB board?

Below factors should be considered when we choose the material for PCB:

The material's Tg value should be greater than the operation temperature;

Low CTE material has good performance of thermal stability;

Good thermal resistance performance: Normally PCBs are required to resist 250°C for at least 50s. Good flatness; In consideration of the electrical properties, low loss/high permittivity material is used on high frequency PCB; Polyimide glass fiber substrate used for flexible PCB; Metal core is used when the product has strict requirement of heat dissipation.

12. What's the merits of O-leading's rIgid-flex PCB?

O-leading's rigid-flex PCB has the characters of both FPC and PCB, so it can be used in some special products. Some part is flexible while the other part rigid, it can help save product's interior space, reduce product volume and improve performance.

13. How to you make the impedance calculation?

The impedance control system is done using some test coupons, the SI6000 soft and the CITS 500s equipment from POLAR INSTRUMENTS.

The equipment measures the impedance on a representative track configuration coupon of which the client has given us a determinate value and tolerance.